TE Internal #: 5177827-3

TE Internal Description: M3 SOCKET

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets



DRAM Type: **Standard**Number of Positions: **72**

Termination Method to PCB: Surface Mount

Module Orientation: Right Angle
Centerline (Pitch): 1.27 mm [.05 in]

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Standard
Configuration Features	
Number of Keys	1
Number of Rows	2
Number of Positions	72
Module Orientation	Right Angle
Electrical Characteristics	

Body Features

DRAM Voltage

Retention Post Location	None
Latch Material	Copper Alloy
Connector Profile	Standard
Ejector Location	Both Ends
Ejector Material	Copper Alloy
Ejector Type	Locking

5 V

Contact Features

PCB Contact Termination Area Plating Material Thickness	2 μm[78.7 μin]
Socket Style	M3 (Mini Memory Module)
Contact Mating Area Plating Material	Gold Flash

M3 SOCKET



Memory Socket Type	Memory Card
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material Thickness	.3 μm[11.81 μin]

Termination Features

Insertion Style	Cam-In
Termination Method to PCB	Surface Mount

Mechanical Attachment

Mount Angle	Right Angle
PCB Mount Retention Type	Solder Tail
Mating Alignment Type	None
PCB Mount Retention	Without

Housing Features

Housing Material	LCP (Liquid Crystal Polymer)
Housing Color	Natural
Centerline (Pitch)	1.27 mm[.05 in]

Dimensions

Profile Height from PCB	5.5 mm[.21 in]
Row-to-Row Spacing	5.2 mm[.2 in]

Industry Standards

Packaging Features

Packaging Quantity	35
Packaging Method	Box & Tray, Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247)



Candidate List Declared Against: JUL 2019 (201)

Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC

Free

Solder Process Capability

Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Customers Also Bought





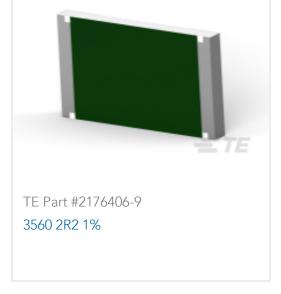








90X2.00MM









Documents

CAD Files

3D PDF

English

Customer View Model

ENG_CVM_5177827-3_O.2d_dxf.zip

English

Customer View Model

ENG_CVM_5177827-3_O.3d_igs.zip

English

Customer View Model

ENG_CVM_5177827-3_O.3d_stp.zip

English

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